

### SUBMINIATURE SOLID STATE LAMP

PRELIMINARY SPEC

Part Number: AM2520SYCK09

Super Bright Yellow

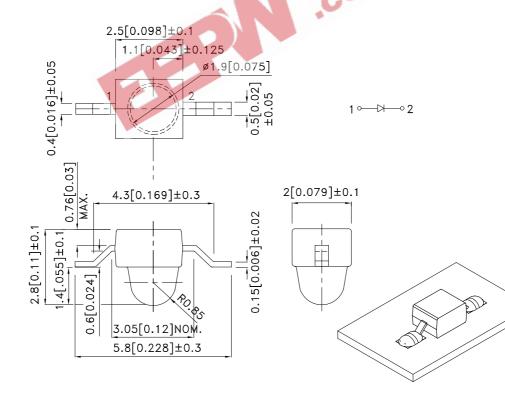
### **Features**

- SUBMINIA TURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- PACKAGE: 1000PCS / REEL.
- RoHS COMPLIANT.

## **Description**

The Super Bright Yellow device is made with DH InGaAlP (on GaAs substrate) light emitting diode chip.

## **Package Dimensions**



### Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.





 SPEC NO: DSAD1289
 REV NO: V.5
 DATE: MAY/08/2007
 PAGE: 1 OF 5

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Y.L.LI
 ERP: 1202000720

## **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM2520SYCK09	Super Bright Yellow (InGaAIP)	WATER CLEAR	650	1300	20°

- 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590	. 4	nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590	30	nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	IF=20mA
С	Capacitance	Super Bright Yellow	20	44.	pF	V <sub>F</sub> =0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	I=20mA
lR	Reverse Current	Super Bright Yellow		10	uA	V <sub>R</sub> =5V

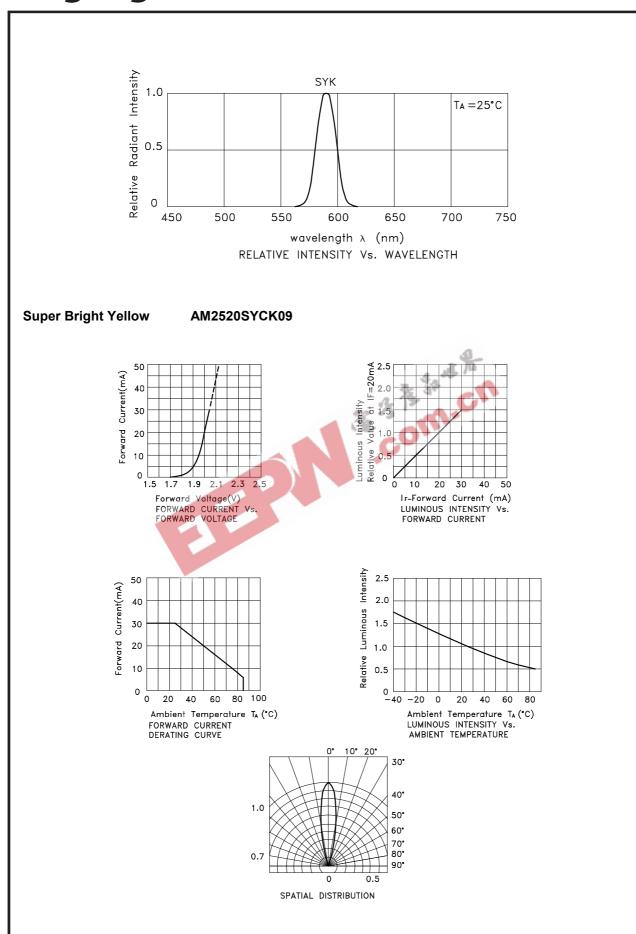
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

7.000 in a 2011 in 1.2011					
Parameter	Super Bright Yellow	Units			
Power dissipation	75	mW			
DC Forward Current	30	mA			
Peak Forward Current [1]	175	mA			
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

SPEC NO: DSAD1289 **REV NO: V.5** DATE: MAY/08/2007 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.L.LI ERP: 1202000720

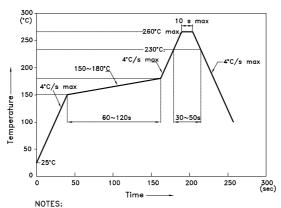


 SPEC NO: DSAD1289
 REV NO: V.5
 DATE: MAY/08/2007
 PAGE: 3 OF 5

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## **AM2520SYCK09**

Reflow Soldering Profile For Lead-free SMT Process.



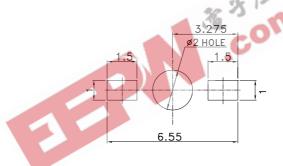
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

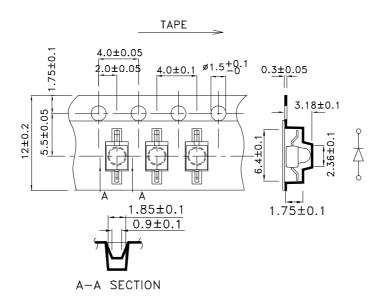
  3.Number of reflow process shall be 2 times or less.

## **Recommended Soldering Pattern**

(Units: mm; Tolerance: ± 0.1)

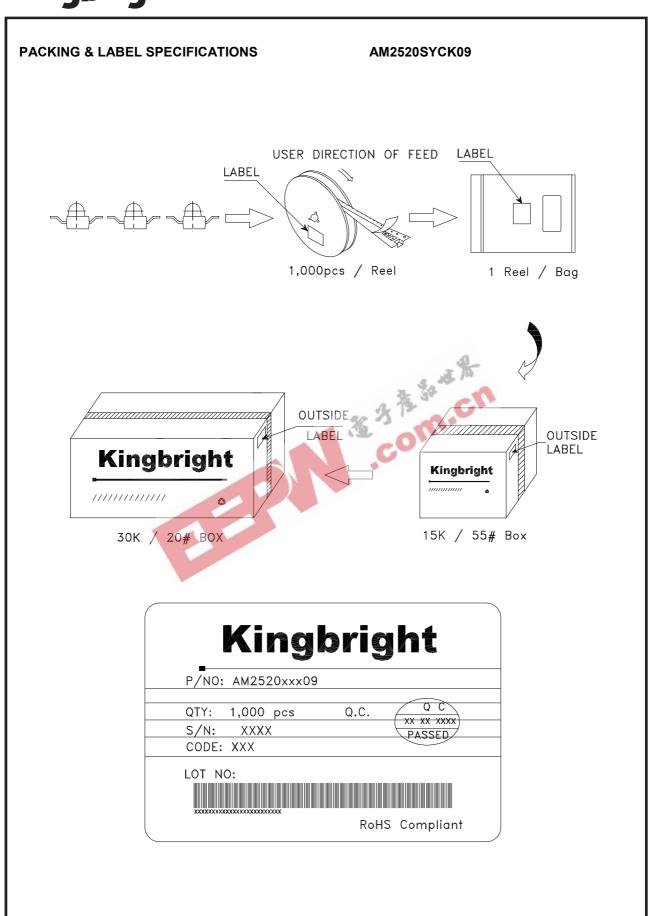


**Tape Specifications** (Units: mm)



SPEC NO: DSAD1289 **REV NO: V.5 APPROVED: WYNEC CHECKED: Allen Liu** 

**DATE: MAY/08/2007** PAGE: 4 OF 5 DRAWN: Y.L.LI ERP: 1202000720



SPEC NO: DSAD1289
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REV NO: V.5 CHECKED: Allen Liu DATE: MAY/08/2007 DRAWN: Y.L.LI PAGE: 5 OF 5 ERP: 1202000720